



/ Revised record

A	2019.12.10		SOT-363		
A	2021-2-2	all	BR3RC5211WS BRMUN5211WS		
B	2021-11-25	4			

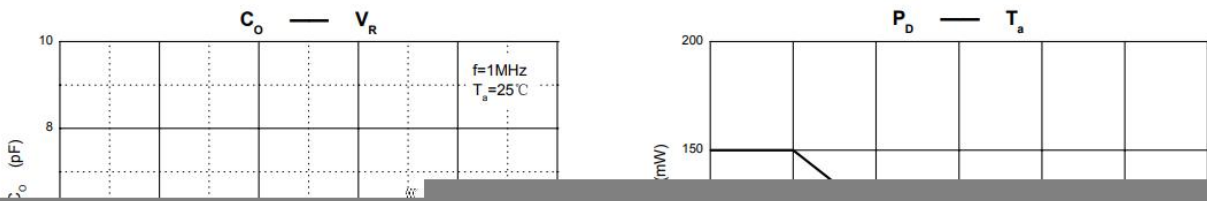
/ Absolute Maximum Ratings(Each Transistor, $T_a=25$)

Parameter	Symbol	Rating	Unit
Output Voltage	V_{CC}	50	V
Input Voltage	V_{IN}	40	V
		-10	V
Output Current	I_{CM}	100	mA
	I_O	50	mA
Collector Dissipation	P_C	200	mW
Junction Temperature	T_j	150	$^{\circ}C$
Storage Temperature Range	T_{stg}	-55~150	$^{\circ}C$

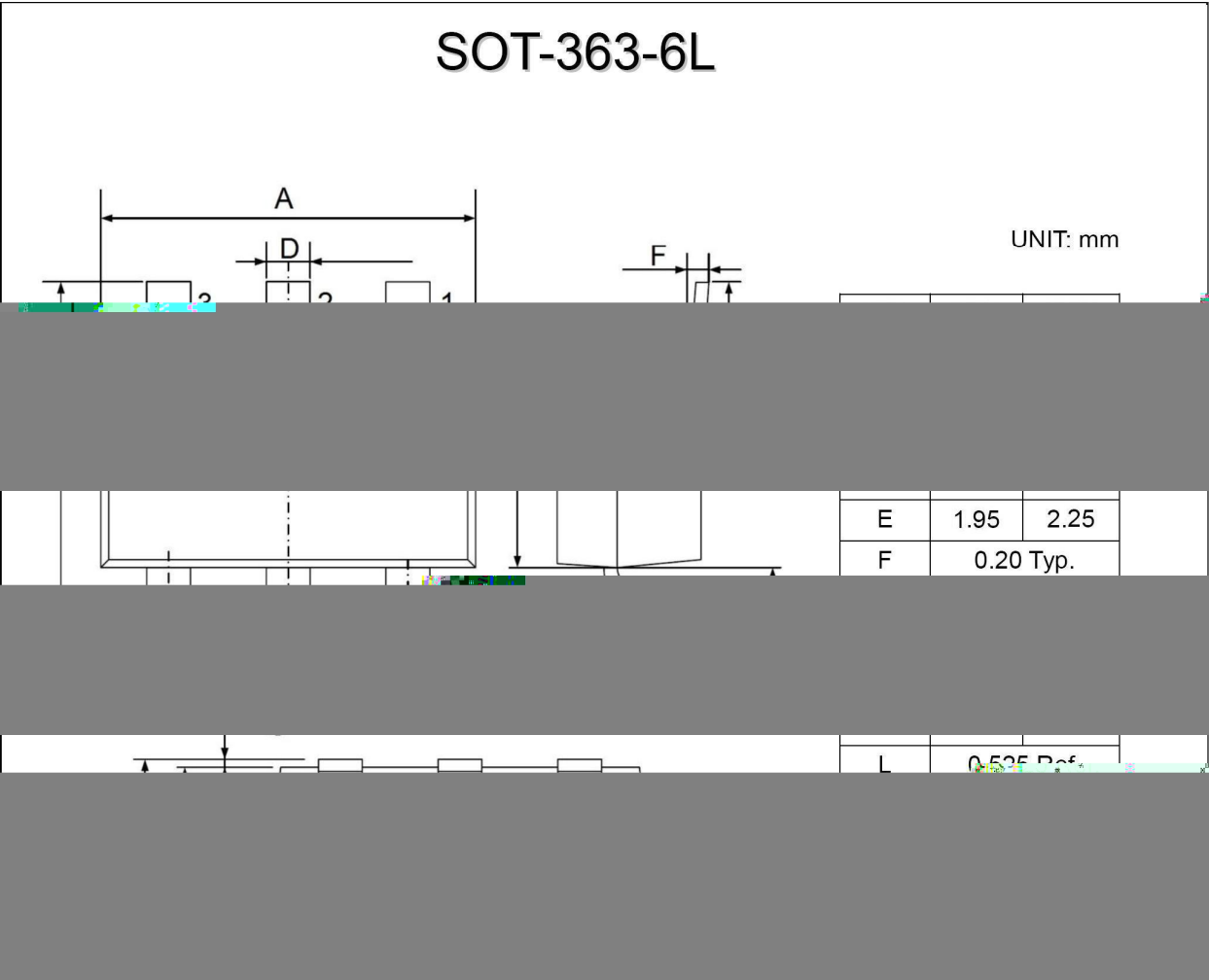
/ Electrical Characteristics((Each Transistor, $T_a=25$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage	$V_{I(off)}$	$V_{CC}=5.0V$ $I_O=100\mu A$			0.5	V
Input Voltage	$V_{I(on)}$	$V_O=0.3V$ $I_O=10mA$	3			V
Output Voltage	$V_{O(on)}$	$I_O=10mA$ $I_I=0.5mA$			0.3	V
Input Current	I_I	$V_I=5.0V$			0.88	mA
Output Cut-off Current	$I_{O(off)}$	$V_{CC}=50V$ $V_I=0V$			0.5	μA
DC Current Gain	G_I	$V_O=5.0V$ $I_O=5.0mA$	30			
Transition Frequency	f_T	$V_{CE}=10V$ $I_C=5.0mA$ $f=100MHz$		250		MHz
Resistance1	R_1		7	10	13	K Ω
Resistance Ratio	R_2/R_1		0.8	1	1.2	

/ Electrical Characteristic Curve



/ Package Dimensions





/ Marking Instructions



" 1 "

H211

***:

Note:



"1" Pin

H211

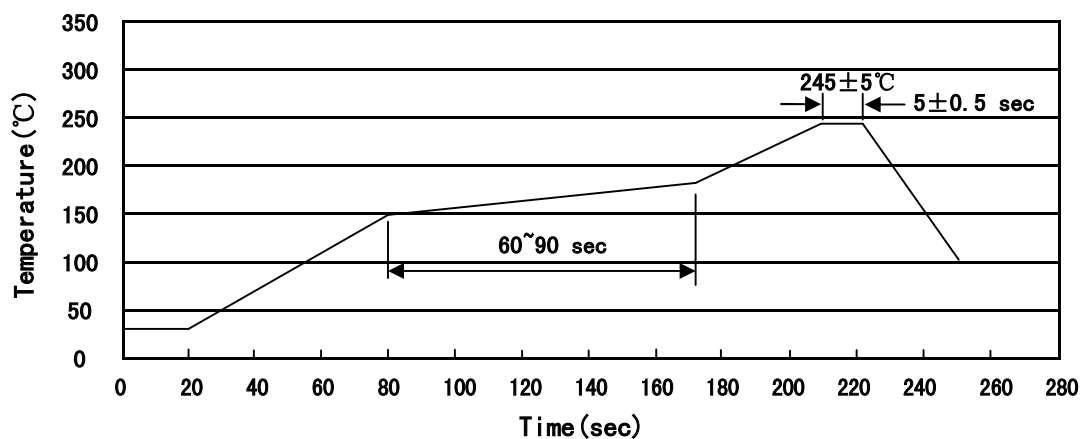
Product Type Code

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Lot No. Code, code change with Lot No.



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----|-----------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5

10±1 sec.

Temp.:260±5°C

Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱
						"		

/ Notices